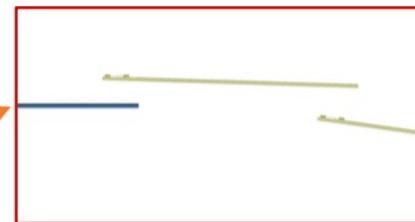
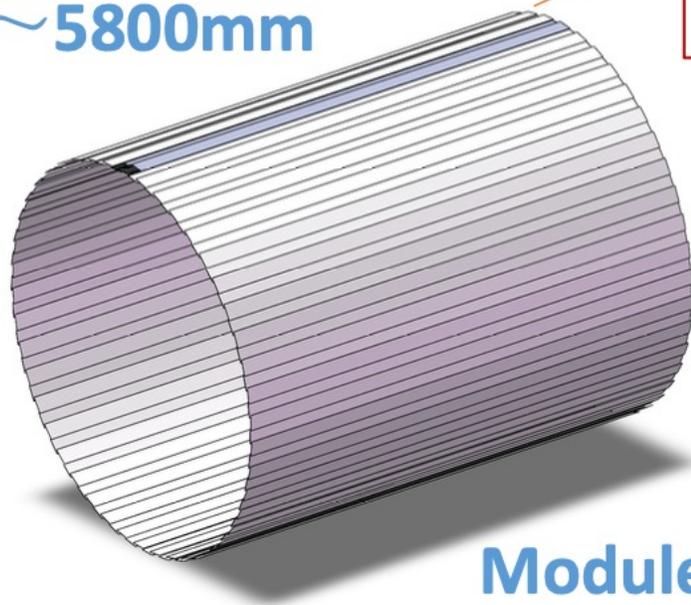


Structure(level 1)

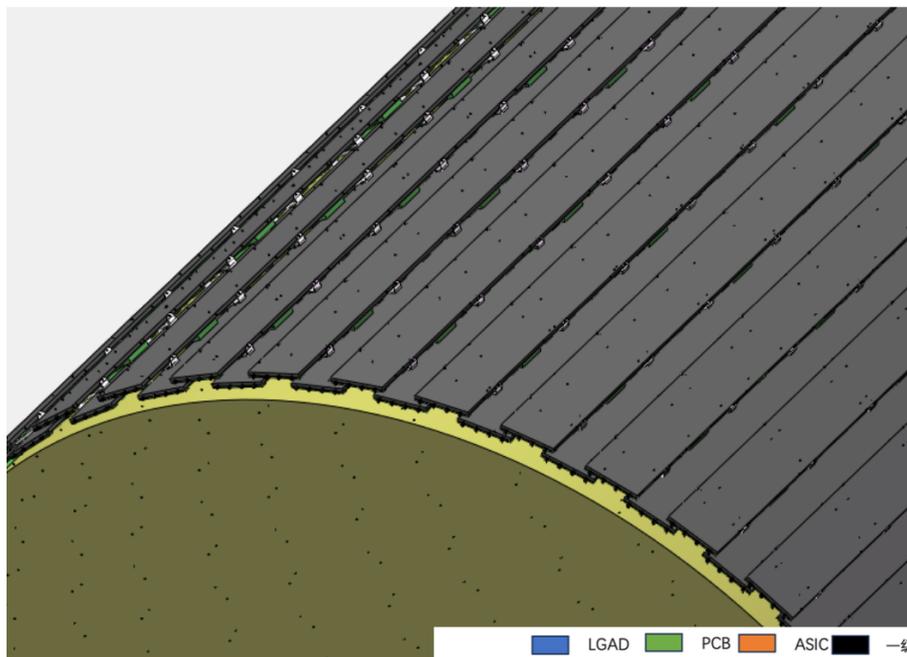


One layer ToF
R= 1800 mm
H~5800mm

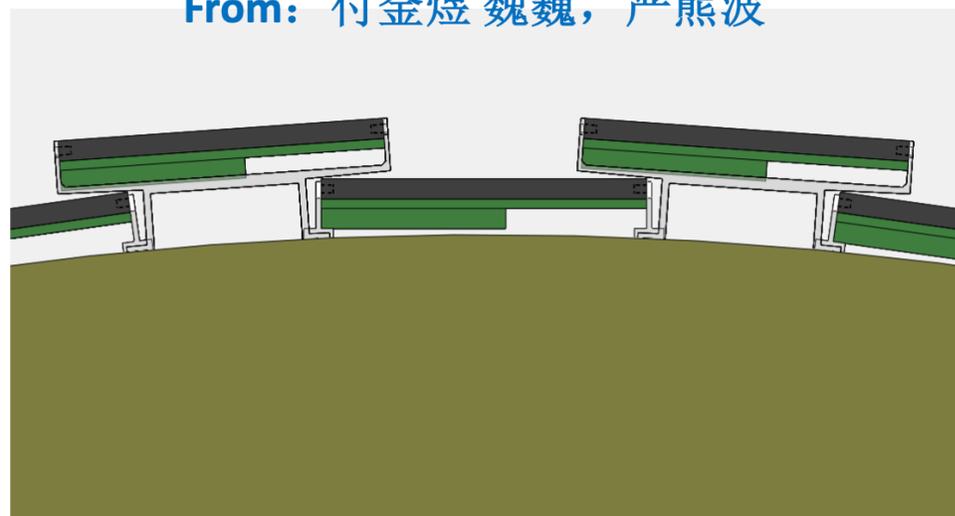


Module

Structure(level 2)



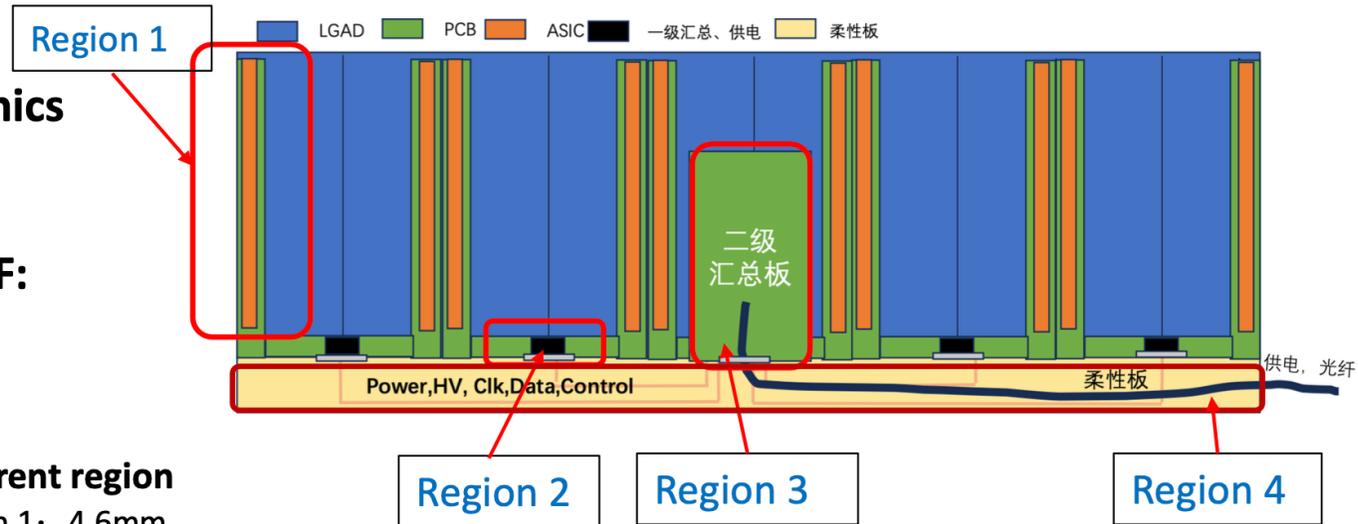
From: 付金煜 魏巍, 严熊波



Structure(level 3)

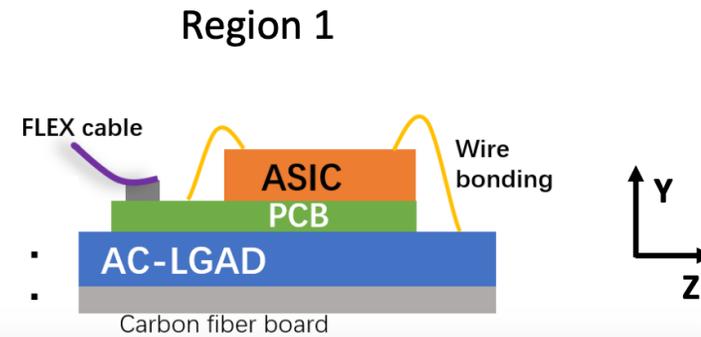


**Thickness of electronics
+ sensor:**
25 mm -> 15.1 mm
Total thickness of ToF:
85 mm -> 58 mm



Detail thicknesses of different region

- The thickness of the region 1: 4.6mm
 - ✓ PCB: 1.6 mm
 - ✓ ASIC: 3 mm
- The thickness of the region 2:
 - ✓ 一级汇总供电: 3 mm
 - ✓ PCB: 1.6 mm
- The thickness of the region 3: **14.6 mm**
 - ✓ 电源模块: 6 mm
 - ✓ 光电复合电缆: 5mm
 - ✓ 弯折走线空间: 2mm
 - ✓ PCB: 1.6 mm
- The thickness of the region 4: 6 mm
 - ✓ 柔性板厚度: 1 mm
 - ✓ 二级汇总供电: 5 mm (高低压供电, 光纤)

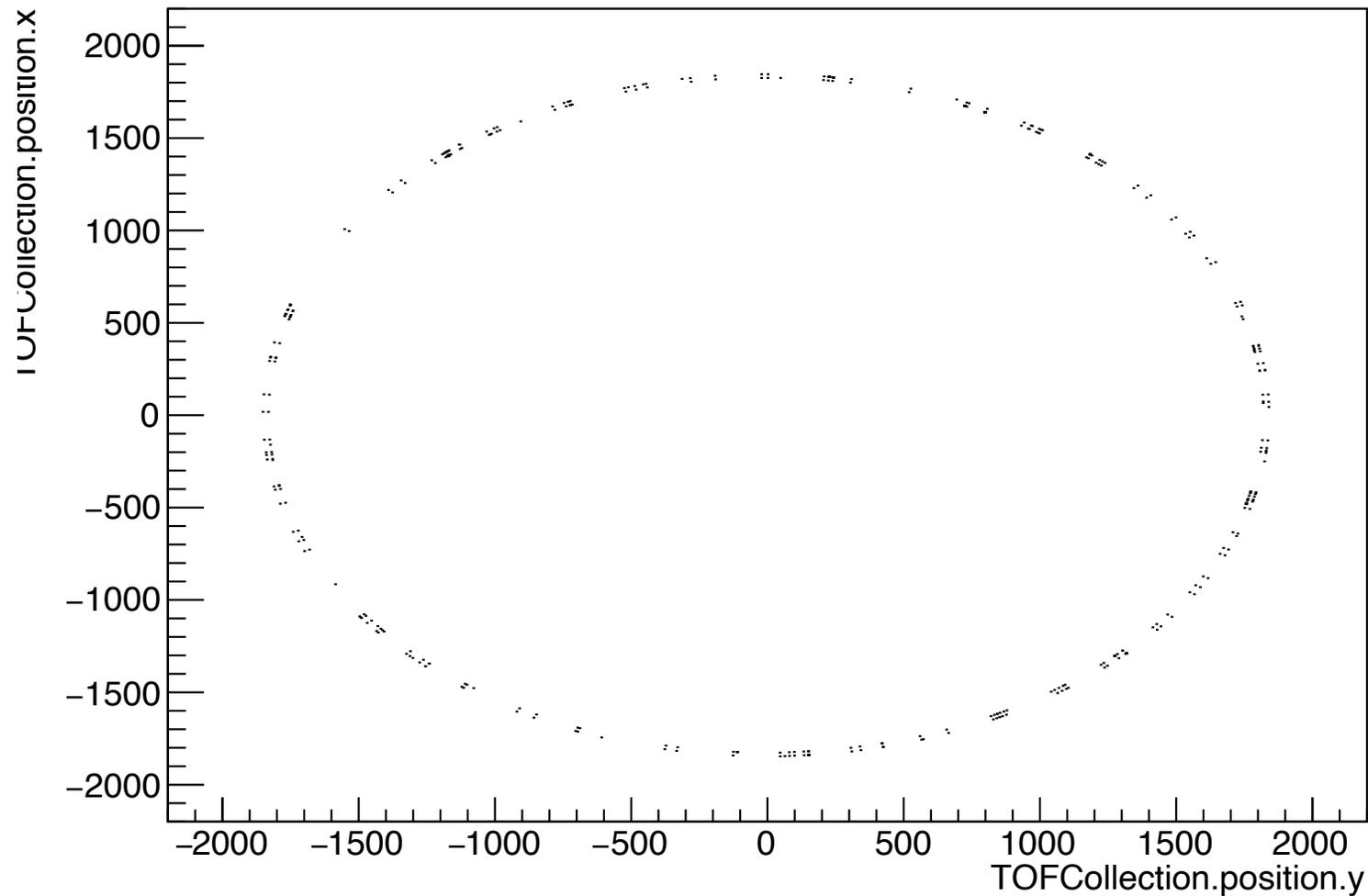


Region 4 is ok

Simulation results



TOFCollection.position.x:TOFCollection.position.y





Finish region 1~3

Optimize cable alignment